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02/10/2004 14:14 FAX 609 275 1010

WATOV AND KIPNES

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## WATOV & KIPNES

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RELATED MATTERS

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### FACSIMILE TRANSMISSION

DATE: February 10, 2004

TO: Office of Initial Patent Examination's Filing Receipt Corrections

RECEIVING FAX TELEPHONE NUMBER: (703) 746-9195

FROM: **KENNETH WATOV**

TRANSMITTING FAX TELEPHONE NUMBER: **(609) 275-1010**

NUMBER OF PAGES: 5, including cover sheet

CONFIRMATION TELEPHONE NUMBER: **(609) 243-0330**

In re Application of:

Applicant	:	Kin P. Cheung
Serial No.	:	10/691,029
Filed	:	October 22, 2003
For	:	PROCESSES FOR HERMETICALLY PACKAGING WAFER LEVEL MICROSCOPIC STRUCTURES
Examiner	:	(Unknown)
Group Art Unit:	:	2818
Atty. Docket No.	:	879.1.004

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KW021004/8791004.RFC

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

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FACSIMILE CERTIFICATE	
DATE	February 10, 2004
I HEREBY CERTIFY THAT, ON THE DATE INDICATED ABOVE, I FACSIMILED THIS PAPER TO THE OFFICE OF INITIAL PATENT EXAMINATION'S FILING RECEIPT CORRECTIONS, FACSIMILE NUMBER 703-746-9195.	
NAME (PRINT)	Kenneth Watov
SIGNATURE	<i>Kenneth Watov</i>

February 10, 2004

VIA FACSIMILE

Office of Initial Patent Examination's Filing Receipt Corrections  
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 Alexandria, VA 22313-1450

REQUEST FOR CORRECTION OF FILING RECEIPT

Dear Sir:

Transmitted herewith is a marked copy of the Filing Receipt (Confirmation No. 7559) in the above-referenced Application showing changes thereon for correction.

Also enclosed is a copy of the Filing Receipt (Confirmation No. 8105) for Provisional Serial No. 60/420,322 clearly showing a filing date of "10/23/02." Applicant claims the benefit of

KW021004/8791004.RFC

the latter, and requests that the Filing Receipt for the above-captioned Serial No. 10/691,029 be corrected to show the 10/23/02 filing date for 60/420,322.

The undersigned respectfully requests confirmation of the receipt of this facsimile by the Office of Initial Patent Examination.

Respectfully submitted,



Kenneth Watov, Esq.  
Registration No. 26,042  
Attorney for Applicant

ADDRESS ALL CORRESPONDENCE TO:

Kenneth Watov, Esq.  
WATOV & KIPNES, P.C.  
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## UNITED STATES PATENT AND TRADEMARK OFFICE

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/691,029	10/22/2003	2818	525	879.1.004	9	26	5

## CONFIRMATION NO. 7559

Kenneth Watov, Esq.  
 Watov & Kipnes, P.C.  
 P.O. Box 247  
 Princeton Junction, NJ 08550

## FILING RECEIPT



\*OC000000011773373\*

Date Mailed: 01/28/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Kin P. Cheung, Hoboken, NJ;

## Domestic Priority data as claimed by applicant

This appn claims benefit of 60/430,322 12/02/2002 *10/23/02*  
 (\*)Data provided by applicant is not consistent with PTO records.

## Foreign Applications

If Required, Foreign Filing License Granted: 01/28/2004

Projected Publication Date: 06/03/2004

Non-Publication Request: No

Early Publication Request: No

\*\* SMALL ENTITY \*\*

## Title

Processes for hermetically packaging wafer level microscopic structures

## Preliminary Class

Page 1 of 2  
03-0  
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Commissioner for Patents  
Washington, D.C. 20231  
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
60/420,322	10/23/2002		80	03-046		1	

27461  
RUTGERS, THE STATE UNIVERSITY  
ATTN: VINCENT SMERAGLIA  
58 BEVIER ROAD  
PISCATAWAY, NJ 08854

CONFIRMATION NO. 8105  
FILING RECEIPT



\*OC000000009182451\*

Date Mailed: 12/02/2002

Receipt is acknowledged of this provisional Patent Application. It will not be examined for patentability and will become abandoned not later than twelve months after its filing date. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

**Applicant(s)**

Kin P. Cheung, Piscataway, NJ;

**If Required, Foreign Filing License Granted:** 12/02/2002

**Projected Publication Date:** None, application is not eligible for pre-grant publication

**Non-Publication Request:** No

**Early Publication Request:** No

**\*\* SMALL ENTITY \*\***

**Title**

Method to produce localized vacuum seal at wafer level for low cost high reliability packaging

**LICENSE FOR FOREIGN FILING UNDER**

**Title 35, United States Code, Section 184**

**Title 37, Code of Federal Regulations, 5.11 & 5.15**

**GRANTED**

DEC